[0395]

[Table 1]

				Example 1	Example 2	Example 3	Example 4	Example 5	Example 6
Contained component (amount(part by mass)) of thermosetting resin layer forming composition	Polymer component		(A)-1	830	830	830	830	830	830
	Epoxy resin		(B1)-1	690	690	690	690	690	690
			(B1)-2	490	490	490	490	490	490
			(B1)-3	770	770	770	770	770	770
	Thermal curing agent		(B2)-1	970	970	970	970	970	970
	Curing accelerator		(C)-1	10	10	10	10	10	10
	Filler		(D)-1	900	900	900	900	450	200
			(D)-2	-	-	-	-	-	-
			(D)-3	-	-	-	-	-	-
	Coloring agent		(I)-1	5	10	15	20	8	8
Amount (% by mass) of filler of thermosetting resin layer				19.3	19.3	19.3	19.2	10.7	5.0
Amount (% by mass) of coloring agent of thermosetting resin layer				0.1	0.2	0.3	0.4	0.2	0.2
Evaluation of thermosetting resin layer and cured material thereof	Transmittance (%) of visible light (550 nm)		Before curing	15	11	8	7	20	35
			After curing	15	11	8	7	20	35
	Concealing property of circuit surface		Before curing	A	A	A	A	A	B
			After curing	A	A	A	A	A	B
	Transmittance (%) of infrared (1600 nm)		Before curing	65	53	46	41	80	95
			After curing	65	53	46	41	80	95
	Observability of circuit surface		Before curing	A	A	B	B	A	A
			After curing	A	A	B	B	A	A
	L^*, a^*, and b^* color system	L*	Before curing	25	16	9	5	30	34
			After curing	25	16	9	5	30	34
		a*	Before curing	12	12	12	12	12	12
			After curing	12	12	12	12	12	12
		b*	Before curing	20	20	20	20	20	20
			After curing	20	20	20	20	20	20
	Color difference (ΔE)		Before curing	32.77	39.15	44.74	48.10	29.81	27.87
			After curing	32.77	39.15	44.74	48.10	29.81	27.87

[0396]

[Table 2]

				Comparative Example 1	Comparative Example 2	Comparative Example 3	Comparative Example 4	Comparative Example 5
Contained component (amount(part by mass)) of thermosetting resin layer forming composition	Polymer component		(A)-1	830	830	830	830	830
	Epoxy resin		(B1)-1	690	690	690	690	690
			(B1)-2	490	490	490	490	490
			(B1)-3	770	770	770	770	770
	Thermal curing agent		(B2)-1	970	970	970	970	970
	Curing accelerator		(C)-1	10	10	10	10	10
	Filler		(D)-1	900	900	-	-	100
			(D)-2	-	-	900	-	-
			(D)-3	-	-	-	900	-
	Coloring agent		(I)-1	50	0	10	10	8
Amount (% by mass) of filler of thermosetting resin layer				19.1	19.3	19.3	19.3	2.6
Amount (% by mass) of coloring agent of thermosetting resin layer				1.1	0	0.2	0.2	0.2
Evaluation of thermosetting resin layer and cured material thereof	Transmittance (%) of visible light (550 nm)		Before curing	1	50	15	10	48
			After curing	1	50	15	10	48
	Concealing property of circuit surface		Before curing	A	D	A	A	C
			After curing	A	D	A	A	C
	Transmittance (%) of infrared (1600 nm)		Before curing	13	74	30	26	96
			After curing	13	74	30	26	96
	Observability of circuit surface		Before curing	D	A	C	C	A
			After curing	D	A	C	C	A
	L^*, a^*, and b^* color system	L*	Before curing	1	43	5	4	44
			After curing	1	43	5	4	44
		a*	Before curing	12	12	-12	-15	12
			After curing	12	12	-12	-15	12
		b*	Before curing	20	20	24	26	20
			After curing	20	20	24	26	20
	Color difference (ΔE)		Before curing	51.55	25.33	50.89	53.62	25.23
			After curing	51.55	25.33	50.89	53.62	25.23